

Electronic Patent Application Fee Transmittal

Application Number:	10616097			
Filing Date:	08-Jul-2003			
Title of Invention:	Multiple-step electrodeposition process for direct copper plating on barrier metals			
First Named Inventor/Applicant Name:	Zhi-Wen Sun			
Filer:	Keith Patrick Taboada			
Attorney Docket Number:	AMAT/8241/CMP/ECP/RKK			

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 1 month with \$0 paid	1251	1	130	130
-----------------------------------	------	---	-----	-----

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130